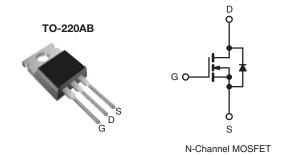


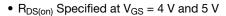
Power MOSFET

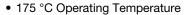
PRODUCT SUMMARY						
V _{DS} (V)	60	60				
R _{DS(on)} (Ω)	$V_{GS} = 5.0 \text{ V}$	0.20				
Q _g (Max.) (nC)	8.4	8.4				
Q _{gs} (nC)	3.5	3.5				
Q _{gd} (nC)	6.0	6.0				
Configuration	Sing	Single				



FEATURES

- Dynamic dV/dt Rating
- · Logic-Level Gate Drive





- Fast Switching
- · Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	IRLZ14PbF			
Lead (FD)-free	SiHLZ14-E3			
SnPb	IRLZ14			
SIIFD	SiHLZ14			

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V_{DS}	60	V	
Gate-Source Voltage			V _{GS}	± 10	V	
Continuous Drain Current	V _{GS} at 5.0 V	T _C = 25 °C		10	А	
Continuous Drain Current	V _{GS} at 5.0 V	T _C = 100 °C	I _D	7.2		
Pulsed Drain Current ^a			I _{DM}	40	1	
Linear Derating Factor				0.29	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	39.5	mJ	
Maximum Power Dissipation	aximum Power Dissipation T _C = 25 °C			43	W	
Peak Diode Recovery dV/dt ^c			dV/dt	4.5	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 175	°C	
Soldering Recommendations (Peak Temperature)	for 10 s			300 ^d		
Mounting Toyour	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. V_{DD} = 25 V, starting T_J = 25 °C, L = 0.79 mH, R_g = 25 Ω , I_{AS} = 10 A (see fig. 12).
- c. $I_{SD} \le 10$ A, $dI/dt \le 90$ A/µs, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C.
- d. 1.6 mm from case.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply



THERMAL RESISTANCE					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	-	62	
Case-to-Sink, Flat, Greased Surface	R _{thCS}	-	0.50	-	°C/W
Maximum Junction-to-Case (Drain)	R _{thJC}	-	-	3.5	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							•
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0 V, I _D = 250 μA	60	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.070		V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	1.0	-	2.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 10 V	-	-	± 100	nA
Zava Cata Valtaga Dvain Cuwant		V _{DS} = 60 V, V _{GS} = 0 V		-	-	25	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 48 V	, V _{GS} = 0 V, T _J = 150 °C	-	-	250	μA
Drain-Source On-State Resistance	В	V _{GS} = 5.0 V	$I_D = 6.0 \text{ A}^b$	-	-	0.20	0
Drain-Source On-State nesistance	R _{DS(on)}	V _{GS} = 4.0 V	$I_D = 5.0 A^b$	-	-	0.28	Ω
Forward Transconductance	9 _{fs}	V _{DS} :	= 25 V, I _D = 6.0 A ^b	3.5	-	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$	-	400	-	
Output Capacitance	C _{oss}	1 .	$V_{DS} = 25 \text{ V},$	-	170	-	pF
Reverse Transfer Capacitance	C _{rss}	f = 1	V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		42	-	1
Total Gate Charge	Qg			-	-	8.4	
Gate-Source Charge	Q _{gs}	V _{GS} = 5.0 V	$I_D = 10 \text{ A}, V_{DS} = 48 \text{ V}$ see fig. 6 and 13 ^b	-	-	3.5	nC
Gate-Drain Charge	Q_{gd}		ooo ngi o ana ro	-	-	6.0	
Turn-On Delay Time	t _{d(on)}			-	9.3	-	
Rise Time	t _r	V _{DD} = 30 V, I _D = 10 A		-	110		
Turn-Off Delay Time	t _{d(off)}	$R_g = 12 \Omega, R_D = 2.8 \Omega$ see fig. 10^b		-	17	-	ns
Fall Time	t _f	See lig. 10		-	26	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nН
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10	Α
Pulsed Diode Forward Current ^a	I _{SM}			-	-	40	
Body Diode Voltage	V_{SD}	T _J = 25 °C	C, I _S = 10 A, V _{GS} = 0 V ^b	-	-	1.6	V
Body Diode Reverse Recovery Time	t _{rr}	T. =	25 °C, I _F = 10 A.	-	93	130	ns
Body Diode Reverse Recovery Charge	Q _{rr}	dl	25 °C, I _F = 10 A, /dt = 100 A/µs ^b	-	0.34	0.65	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	rn-on time is negligible (turr	-on is dor	minated h	v L _s and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

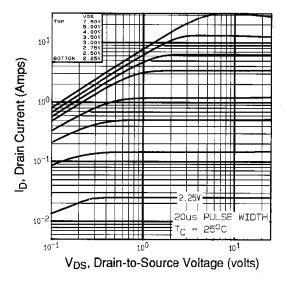


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

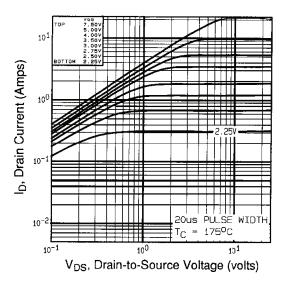


Fig. 2 - Typical Output Characteristics, $T_C = 175$ °C

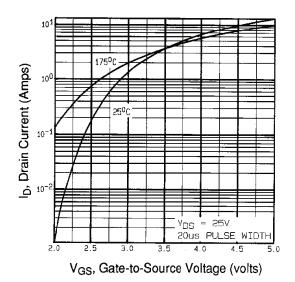


Fig. 3 - Typical Transfer Characteristics

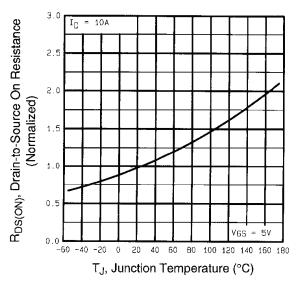


Fig. 4 - Normalized On-Resistance vs. Temperature



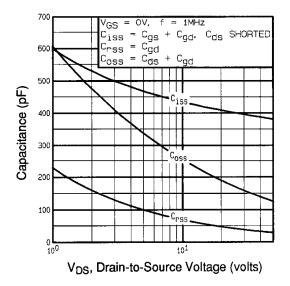


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

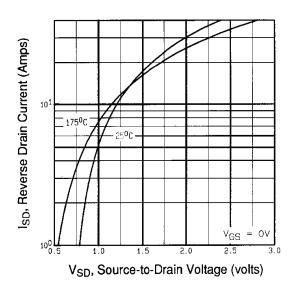


Fig. 7 - Typical Source-Drain Diode Forward Voltage

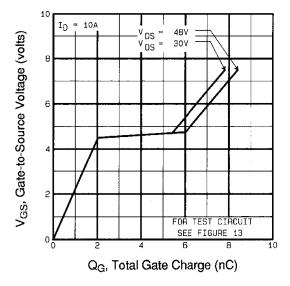


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

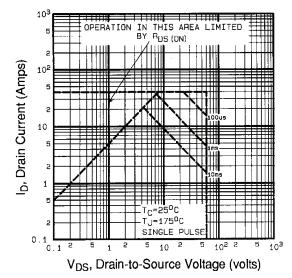


Fig. 8 - Maximum Safe Operating Area





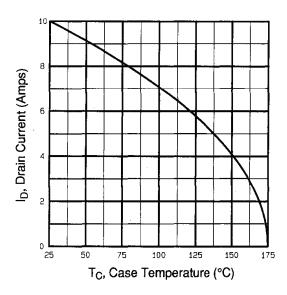


Fig. 9 - Maximum Drain Current vs. Case Temperature

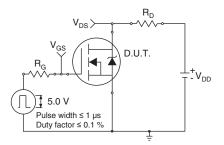


Fig. 10a - Switching Time Test Circuit

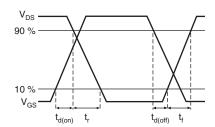


Fig. 10b - Switching Time Waveforms

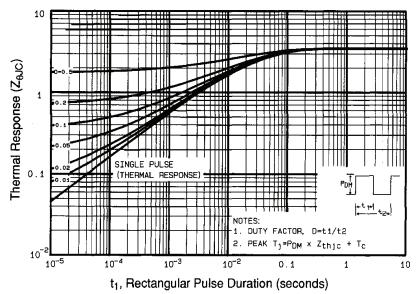


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



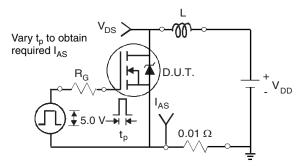


Fig. 12a - Unclamped Inductive Test Circuit

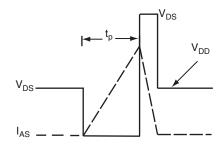


Fig. 12b - Unclamped Inductive Waveforms

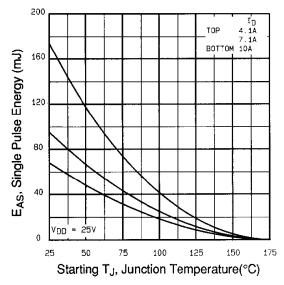


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

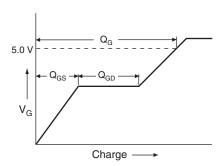


Fig. 13a - Basic Gate Charge Waveform

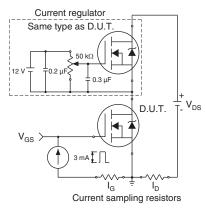
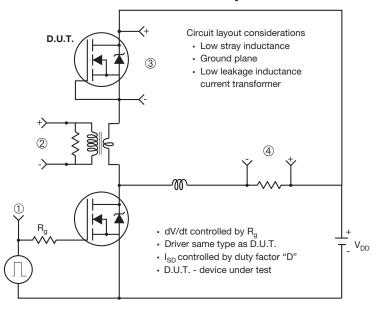


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



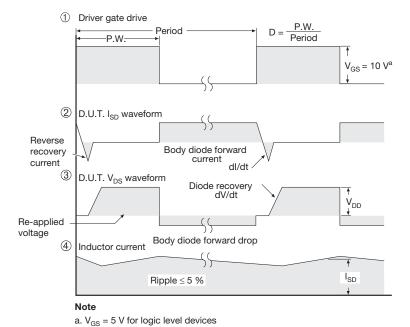


Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	METERS	INCHES		
DIW.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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